CTLSH01-30

SURFACE MOUNT
SILICON SCHOTTKY DIODE

TLP™ Tiny Leadless Package

Top View Bottom View

TLM2D3D6 CASE

Central Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CTLSH01-30 is a high quality Schottky Diode designed for applications where ultra small size and power dissipation are prime requirements. Packaged in a Ultra Tiny Leadless Package™, TLP™, this component provides performance characteristics suitable for the most demanding size constrained applications.

MARKING CODE: C

APPLICATIONS:

- DC - DC Converters
- Voltage Clamping
- Protection Circuits
- Battery powered applications including Cell Phones, Digital Cameras, Pagers, PDAs, Laptop Computers, etc.

FEATURES:

- Current (I_O=100mA)
- Low Forward Voltage Drop (V_F=0.41V TYP @ 10mA)
- Low Reverse Current (30nA TYP @ 10V)
- Ultra Small, Ultra Low Profile 0.3mm x 0.6mm x 0.3mm TLP™ Leadless Surface Mount package

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Average Forward Current	I_O	100	mA
Peak Forward Surge Current, tp=8.3ms	I_{FSM}	500	mA
Power Dissipation	P_D	100	mW
Operating Junction Temperature	T_J	-65 to +125	°C
Storage Temperature	T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	1000	°C/W

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	**TEST CONDITIONS**	**MIN**	**TYP**	**MAX**	**UNITS**
I_R	V_R=10V		30	300	nA
BV_R	I_R=100μA	30			V
V_F	I_F=10mA		0.41	0.46	V
C_T	V_R=0, f=1.0MHz		7.0		pF

R3 (20-April 2011)

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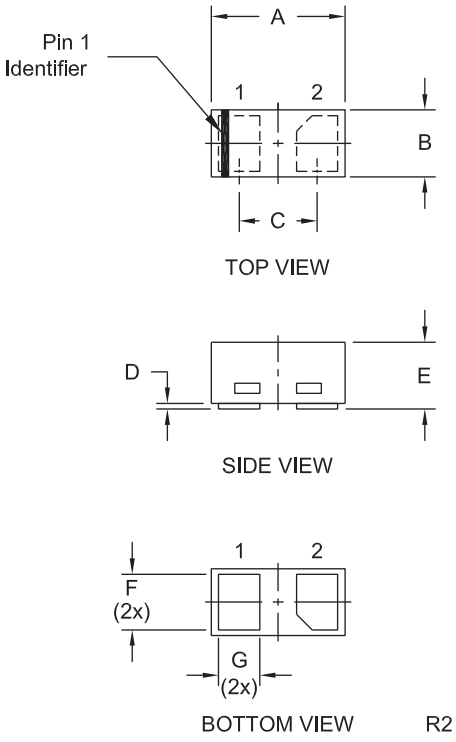
TLM2D3D6 CASE - MECHANICAL OUTLINE



DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.022	0.026	0.55	0.65
B	0.010	0.014	0.25	0.35
C	0.014		0.35	
D	0.000	0.002	0.00	0.05
E	0.011	0.013	0.28	0.32
F	0.008	0.012	0.20	0.30
G	0.005	0.009	0.13	0.24

TLM2D3D6 (REV: R2)

LEAD CODE:
1) Cathode
2) Anode

MARKING CODE: C